TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOS III)

TPC8211

Lithium Ion Battery Applications Portable Equipment Applications Notebook PC Applications

• Low drain-source ON resistance: $RDS(ON) = 25 \text{ m}\Omega \text{ (typ.)}$

• High forward transfer admittance: $|Y_{fs}| = 7.0 \text{ S (typ.)}$

• Low leakage current: $I_{DSS} = 10 \mu A \text{ (max) (V}_{DS} = 30 \text{ V)}$

• Enhancement-mode: $V_{th} = 1.3 \text{ to } 2.5 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$

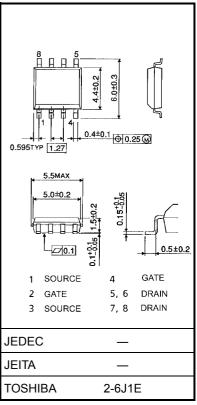
Maximum Ratings (Ta = 25°C)

Char	racteristics	Symbol	Rating	Unit	
Drain-source vol	tage	V_{DSS}	30	V	
Drain-gate volta	ge (R _{GS} = 20 kΩ)	V_{DGR}	30	V	
Gate-source volt	age	V _{GSS}	±20	V	
Drain current	D C (Note 1)	I _D	5.5	Α	
Drain current	Pulse (Note 1)	I _{DP}	22	_ A	
Drain power dissipation (t = 10 s) (Note 2a)	Single-device operation (Note 3a)	P _{D (1)}	1.5	W	
	Single-device value at dual operation (Note 3b)	P _{D(2)}	1.1		
Drain power dissipation (t = 10 s) (Note 2b)	Single-device operation (Note 3a)	P _{D (1)}	0.75	w	
	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.45	vv	
Single pulse ava	lanche energy (Note 4)	E _{AS}	39.3	mJ	
Avalanche curre	nt	I _{AR}	5.5	Α	
Repetitive avalar Single-device va	nche energy lue at dual operation (Note 2a, 3b, 5)	E _{AR}	0.1	mJ	
Channel tempera	ature	T _{ch}	150	°C	
Storage tempera	ture range	T _{stg}	−55 to 150	°C	

Note: For (Note 1), (Note 2), (Note 3), (Note 4) and (Note 5), please refer to the next page.

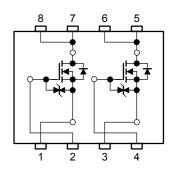
This transistor is an electrostatic sensitive device. Please handle with caution.

Unit: mm



Weight: 0.08 g (typ.)

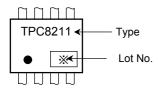
Circuit Configuration



Thermal Characteristics

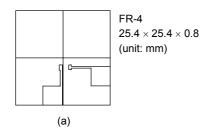
Characteristics	Symbol	Max	Unit		
The small registers as about the crabinat	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	83.3		
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	114	°C/W	
The weed we sintened a channel to crebine	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	167	C/VV	
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	278		

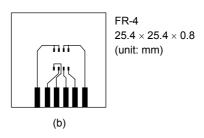
Marking (Note 6)



Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:

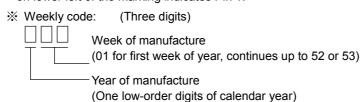




- a) Device mounted on a glass-epoxy board (a)
- b) Device mounted on a glass-epoxy board (b)

Note 3:

- a) The power dissipation and thermal resistance values are shown for a single device. (During single-device operation, power is only applied to one device.)
- b) The power dissipation and thermal resistance values are shown for a single device. (During dual operation, power is evenly applied to both devices.)
- Note 4: V_{DD} = 24 V, T_{ch} = 25°C (initial), L = 1.0 mH, R_G = 25 Ω , I_{AR} = 5.5 A
- Note 5: Repetitive rating: pulse width limited by maximum channel temperature
- Note 6: on lower left of the marking indicates Pin 1.



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Electrical Characteristics (Ta = 25°C)

Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-OFF	rain cut-OFF current		V _{DS} = 30 V, V _{GS} = 0 V		_	10	μA
Drain, acurae breekdown veltage		V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	30	_	I	V
Dialii-source bi	rain-source breakdown voltage		I_D = 10 mA, V_{GS} = -20 V	15	_		
Gate threshold v	oltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	1.3	_	2.5	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 4.5 V, I _D = 3 A		31	44	mΩ
Drain-source ON resistance Forward transfer admittance		R _{DS (ON)}	V _{GS} = 10 V, I _D = 3 A		25	36	11122
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 3 A	3.5	7.0	_	S
Input capacitano	e	C _{iss}		1	1250	1	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	I	155	I	pF
Output capacitance		Coss		1	170	1	
Switching time	Rise time	tr	V_{GS} $\begin{array}{c} 10 \text{ V} \\ 0 \text{ V} \\ \end{array}$ $\begin{array}{c} I_{D} = 3 \text{ A} \\ 0 \text{ V} \\ \end{array}$ $\begin{array}{c} V_{OUT} \\ 0 \text{ V} \\ \end{array}$ $\begin{array}{c} V_{OD} \approx 15 \text{ V} \\ \end{array}$	l	5	ı	
	Turn-ON time	t _{on}		ı	11	ı	- ns
	Fall time	t _f			9	-	
	Turn-OFF time	t _{off}	Duty ≦ 1%, t _w = 10 μs		63	-	
Total gate charge (Gate-source plus gate-drain)		Qg	V _{DD} ≈ 24 V, V _{GS} = 10 V, I _D = 5.5 A	_	25	_	
Gate-source charge		Q_{gs}		_	20	_	nC
Gate-drain ("miller") charge		Q_{gd}		_	5	_	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characte	eristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	_	_	_	22	Α
Forward voltage (diode) V _{DSF}		V _{DSF}	I _{DR} = 5.5 A, V _{GS} = 0 V	_	_	-1.2	V

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